

Amendments to Specification

Page 1, rewrite the paragraph starting at line 12 so as to read as follows:

In Japanese Unexamined Patent Publication JP-A 8-107076 (1996), there is described a CVD (Chemical Vapor Deposition) apparatus for forming a thin film on a surface of a supported wafer. In this CVD apparatus, a susceptor is used as a wafer support mechanism. A wafer is placed on a top of the bearing surface of the susceptor which is horizontally held. When the wafer has been placed, the susceptor is angularly displaced so that the bearing surface is vertical. In this state, a thin film is formed on a top of the wafer. Wafer chuck pins are fixed to the bearing surface. The wafer chuck pins support the wafer on the bearing surface and prevent the wafer from falling due to the angular displacement of the susceptor. After the film has been formed, the susceptor is angularly displaced again so that the bearing surface is ~~vertical~~ horizontal. In this state, the wafer is lifted up and transported away.